

## 6th & 7th CIES Technology Forum VIRTUAL

March 22 (Tue) - 23 (Wed), 2022

## March DAY1

http://www.cies.tohoku.ac.jp/7th\_forum/

## **International Symposium**

Part 1 [Live] 9:00-12:10 (JST)

JST	PDT	CET		
9:00-9:05	March 21 17:00-17:05	1:00-1:05	Opening remarks	Tetsuo Endoh (Tohoku Univ.)
9:05-9:35	17:05-17:35	1:05-1:35	Invited talk 1 Potential of Spintronics Memory and Interestin	Shigeki Tomishima (Intel) g Usage Case
9:35-10:05	17:35-18:05	1:35-2:05	Invited talk 2 Toward low power and high speed SOT-MRAM	Mingyuan Song (TSMC)
10:05-10:35	18:05-18:35	2:05-2:35	Invited talk 3 Development of embedded STT-MRAM for vari	Seungpil Ko (Samsung) ous application and scaling
10:35-11:05	18:35-19:05	2:35-3:05	Invited talk 4 Embedding STT MRAM into high performance,	Thomas Jew (NXP) low leakage micro controller applications
11:05-11:35	19:05-19:35	3:05-3:35	Invited talk 5 Extending GaN integration to higher power and progress and roadmaps for GaN integration	Alex Lidow (Efficient Power Conversion) d faster speeds – an examination of the
11:35-12:05	19:35-20:05	3:35-4:05	Invited talk 6 Integrated power electronics technology apply	Yoshikazu Takahashi (Tohoku Univ.) ing wide-bandgap devices
12:05-12:10	20:05-20:10	4:05-4:10	Closing remarks	Tetsuo Endoh (Tohoku Univ.)

## Part 2 [Streaming] 17:00-20:10 (JST)

JST	PDT	CET		
17:00-17:05	1:00-1:05	9:00-9:05	Opening remarks	Tetsuo Endoh (Tohoku Univ.)
17:05-17:35	1:05-1:35	9:05-9:35	Invited talk 1 Potential of Spintronics Memory and Interestin	Shigeki Tomishima (Intel) g Usage Case
17:35-18:05	1:35-2:05	9:35-10:05	Invited talk 2 Toward low power and high speed SOT-MRAM	Mingyuan Song (TSMC)
18:05-18:35	2:05-2:35	10:05-10:35	Invited talk 3 Development of embedded STT-MRAM for vari	Seungpil Ko (Samsung) ous application and scaling
18:35-19:05	2:35-3:05	10:35-11:05	Invited talk 4 Embedding STT MRAM into high performance,	Thomas Jew (NXP) low leakage micro controller applications
19:05-19:35	3:05-3:35	11:05-11:35	Invited talk 5 Extending GaN integration to higher power and progress and roadmaps for GaN integration	Alex Lidow (Efficient Power Conversion) d faster speeds – an examination of the
19:35-20:05	3:35-4:05	11:35-12:05	Invited talk 6 Integrated power electronics technology apply	Yoshikazu Takahashi (Tohoku Univ.) ing wide-bandgap devices
20:05-20:10	4:05-4:10	12:05-12:10	Closing remarks	Tetsuo Endoh (Tohoku Univ.)

Organizer: Center for Innovative Integrated Electronic Systems (CIES), Tohoku University
Co-sponsored: Research Institute of Electrical Communication (RIEC), Tohoku University

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